

# LVF- 10 – TWO PART LIQUID VOID FILLER

## DATASHEET



### PRODUCT OVERVIEW

- A two-part silicone-based liquid with heat conducting filler and binding materials. When the compound is mixed and cured it acts as a thermally conductive void filling material.

### FEATURES

- Good Thermal Conductivity
- Excellent Dielectric Performance
- Long Life Span
- Weather Resistance.
- Low Mechanical Stress
- Vibration and Shock Absorbance Properties

### APPLICATIONS

- Electronic assemblies, thermistors, temperature sensors, power modules.

PROPERTIES	LVF - 10 PART A	LVF - 10 PART B	LVF - 10 COMBINED	TEST METHOD
Colour	White	Gray		Visual
Mixing ratio	A:B=1:1	A:B=1:1		/
Viscosity	10~30 Pa.S	10~30 Pa.S		ASTM D2196
Specific Gravity	1.847 g/cm <sup>3</sup>	1.839 g/cm <sup>3</sup>		ASTM-D792
Thermal conductivity	1.02 W/mK	1.05 W/mK		ASTM D5470
Viscosity (Mixed)			10~30 Pa.S	ASTM D2196
Thermal conductivity (After curing)			≥0.9 W/mK	ASTM D5470
Specific Gravity (After curing)			1.6 g/cm <sup>3</sup>	ASTM-D792
Flammability Rating (After curing)			V0	UL_94
Volume Resistance (After curing)			≥10 <sup>12</sup> Ohm-cm	ASTM-D257
Breakdown Voltage (1mm) (After curing)			≥5 MPa	ASTM D412
Hardness (After curing)			Shore 00 50	ASTM D2240
Working temperature (After curing)			-40°~180°	/
Curing condition				
Tear strength (After curing)			≥6 N/mm	ASTM D624
Surface drying time (25°C)			20~30 MIN	ASTM D62
Curing time (25°C)			≥50 MIN	/
Curing time (60°C)			10~15 MIN	/
Curing time (100°C)			10~15 MIN	/

### NOTES

- Customised shapes are available
- The above performance data is tested in an environment of 70% humidity, temperature 25 °C
- This data is intended for reference purposes only. It is recommended that the material is tested to fully evaluate its performance ensuring it is fit for purpose.

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